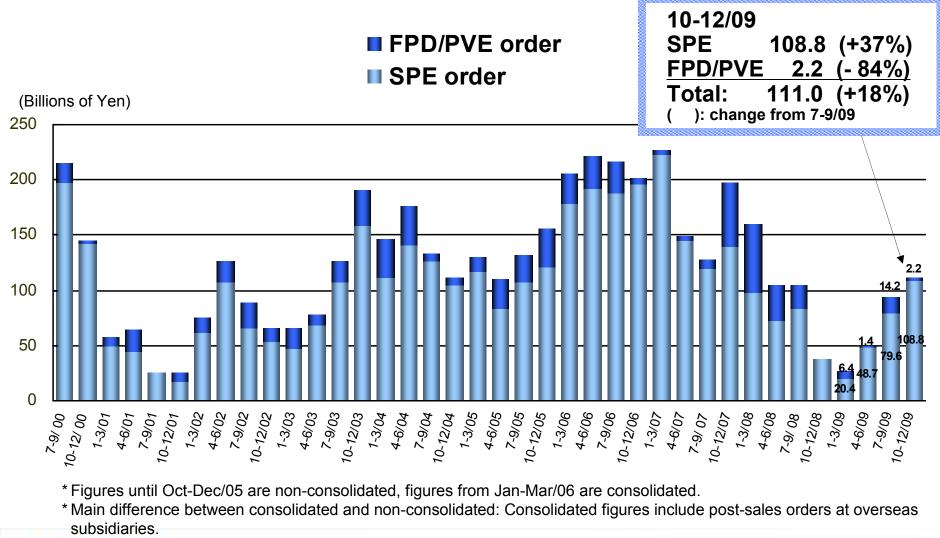
Business Environment

Hiroshi Takenaka, President

February 9, 2010

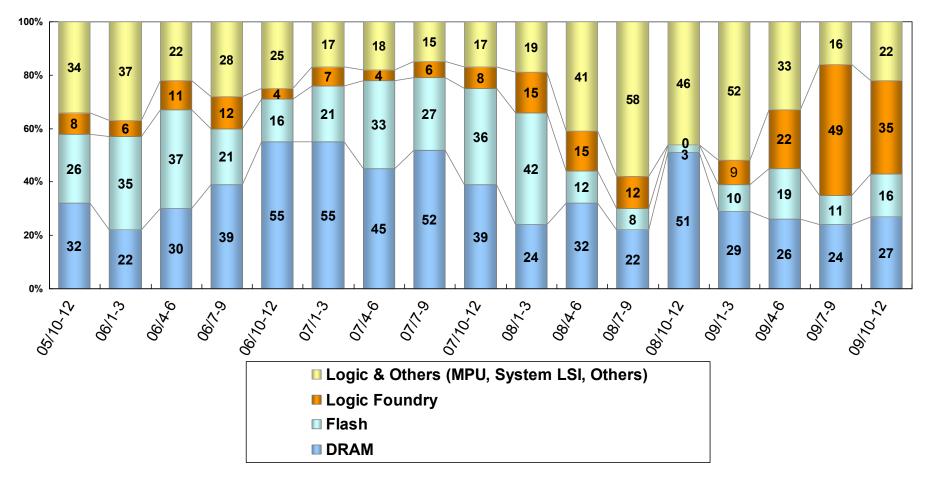


Quarterly SPE+FPD/PVE Orders



CORP IR / February 9, 2010

SPE Orders by Application (Equipment only)





Business Environment in 2010

SPE capex

Continued positive order-booking environment, due to strong consumers demand and reaction to capex reductions in 2009

- NAND: Solid smartphone-related demand, 3xnm capacity investment expected
- DRAM: Major customers expanding scaling investment in 4xnm
- Logic/Foundry: Fab utilization increased, investment in 40nm/32nm continuing

FPD capex

Investment in new fab lines driven by sustained boom in Chinese demand for TVs.

PV capex

Uncertainty still remains, but expecting recovery of capex later this year along with global economic upturn



Restart Plans for New Miyagi Plant

Shorten development/production period of leading-edge etch systems

- Integrate development and mass production functions
- Aim to maximize productivity through supply chain and logistics enhancement
- Secure latest technology and top-class engineers through academic-industrial collaboration

Location:Area:	Taiwa Research Park, Miyagi, Japan 290,569 m²
Construction:	Start summer 2010,
	complete spring 2011 at earliest
Total investment:	25 billion yen

Tokyo Electron Technology Development Institute, Inc. in Sendai City, Miyagi, Japan



Summary

- Expecting larger-scale capex by memory customers, and better business environment
- Further reduced forecast deficit for FY2010 full year, due to increasing sales and good progress on cost cut program. Forecasting 2nd half operating income to turn positive
- Decided to start construction of new Miyagi plant, aiming to strengthen development and mass production functions for leading-edge products

